



US009331128B2

(12) **United States Patent**
Tokuda et al.

(10) **Patent No.:** **US 9,331,128 B2**
(45) **Date of Patent:** **May 3, 2016**

(54) **DISPLAY DEVICE AND MANUFACTURING METHOD THEREOF**

(71) Applicant: **Japan Display Inc.**, Tokyo (JP)

(72) Inventors: **Naoki Tokuda**, Tokyo (JP); **Mitsuhide Miyamoto**, Tokyo (JP)

(73) Assignee: **Japan Display Inc.**, Tokyo (JP)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **14/503,453**

(22) Filed: **Oct. 1, 2014**

(65) **Prior Publication Data**

US 2015/0090993 A1 Apr. 2, 2015

(30) **Foreign Application Priority Data**

Oct. 2, 2013 (JP) 2013-207211

(51) **Int. Cl.**

H01L 27/32 (2006.01)

H01L 51/50 (2006.01)

(52) **U.S. Cl.**

CPC **H01L 27/3246** (2013.01); **H01L 51/50** (2013.01)

(58) **Field of Classification Search**

CPC H01L 27/3246

USPC 438/23, 38; 313/500

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2008/0042559 A1 2/2008 Yamazaki
2009/0009068 A1* 1/2009 Fujimura H01L 27/3276
313/504
2011/0198598 A1* 8/2011 Kim H01L 27/3246
257/59

2014/0183460 A1* 7/2014 Kim H01L 51/56
257/40

2014/0246685 A1* 9/2014 Miura H01L 33/08
257/88

2014/0312323 A1* 10/2014 Park H01L 51/525
257/40

2015/0060826 A1* 3/2015 Matsumoto H01L 27/3246
257/40

2015/0090993 A1* 4/2015 Tokuda H01L 27/3246
257/40

FOREIGN PATENT DOCUMENTS

JP 2009-016231 A 1/2009

JP 2012-22787 A 2/2012

KR 2008-0004385 A 9/2008

KR 2013-0046913 A 2/2013

OTHER PUBLICATIONS

Korean Office Action dated Jan. 7, 2016 for corresponding KR application No. 10-2014-0130178.

* cited by examiner

Primary Examiner — Earl Taylor

(74) *Attorney, Agent, or Firm* — Typha IP LLC

(57) **ABSTRACT**

A display device, includes: a first substrate; an organic planarizing film that is made of an organic insulating material, and arranged on the first substrate; an electrode that comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side; an inorganic bank that is made of an inorganic insulating material, covers an end of the electrode, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side; an OLED layer that covers a side of the electrode and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film; and a sealing film that is configured to cover a side of the OLED layer opposite to the organic planarizing film side.

9 Claims, 13 Drawing Sheets

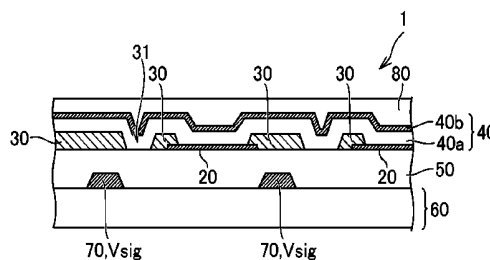
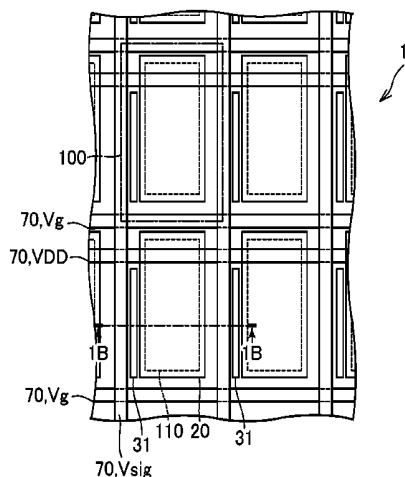


FIG. 1B

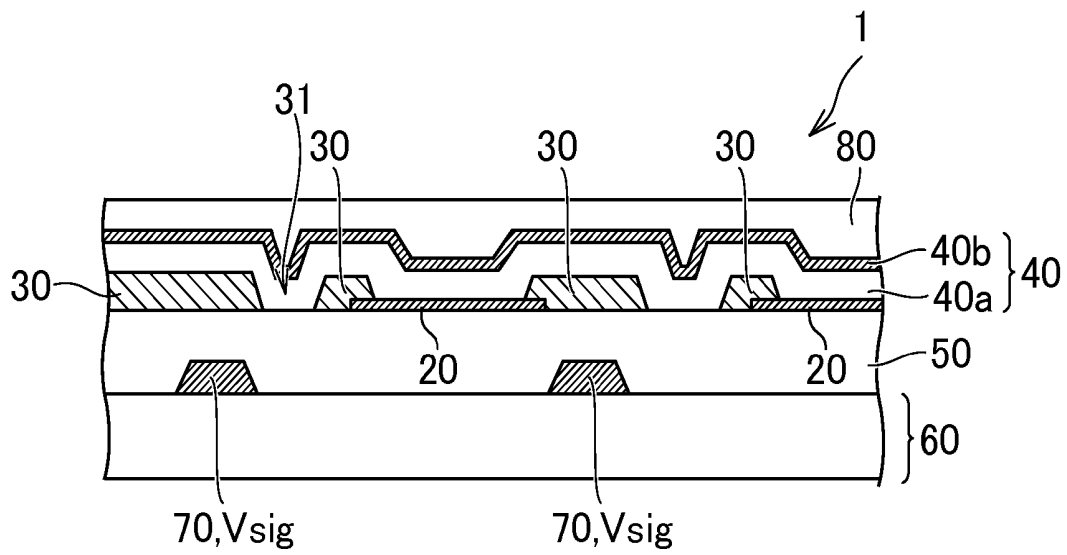


FIG. 2

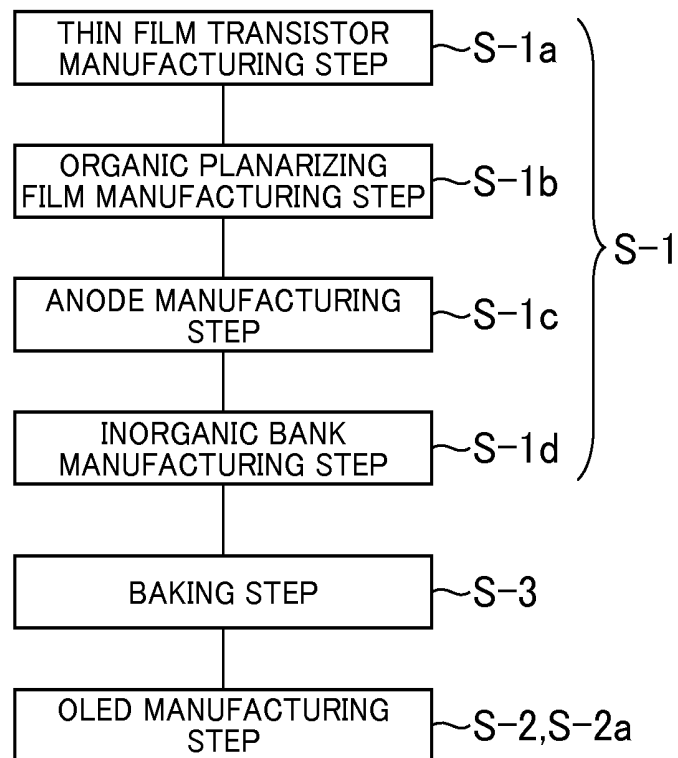


FIG.3B

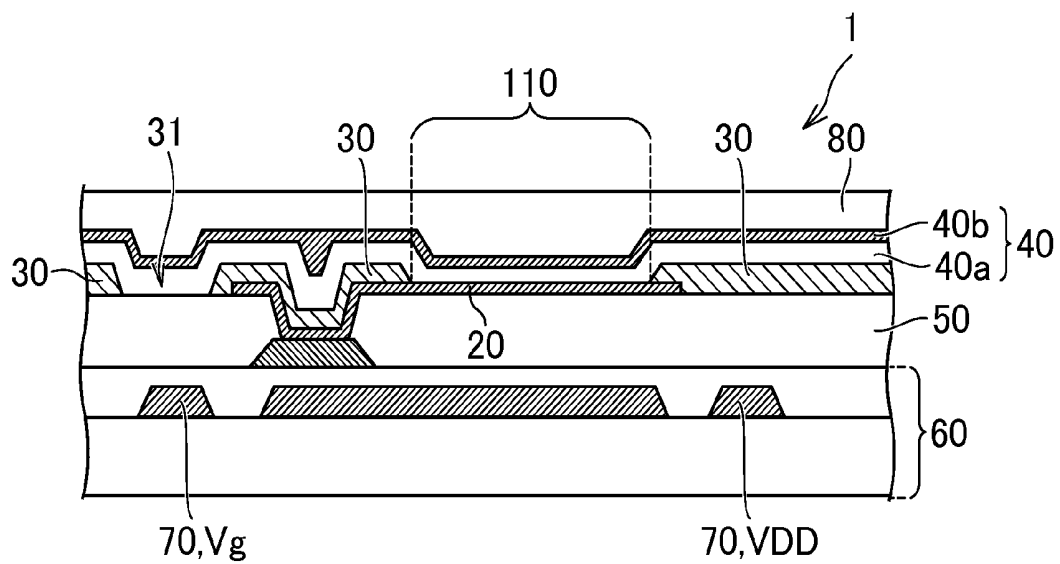


FIG. 4

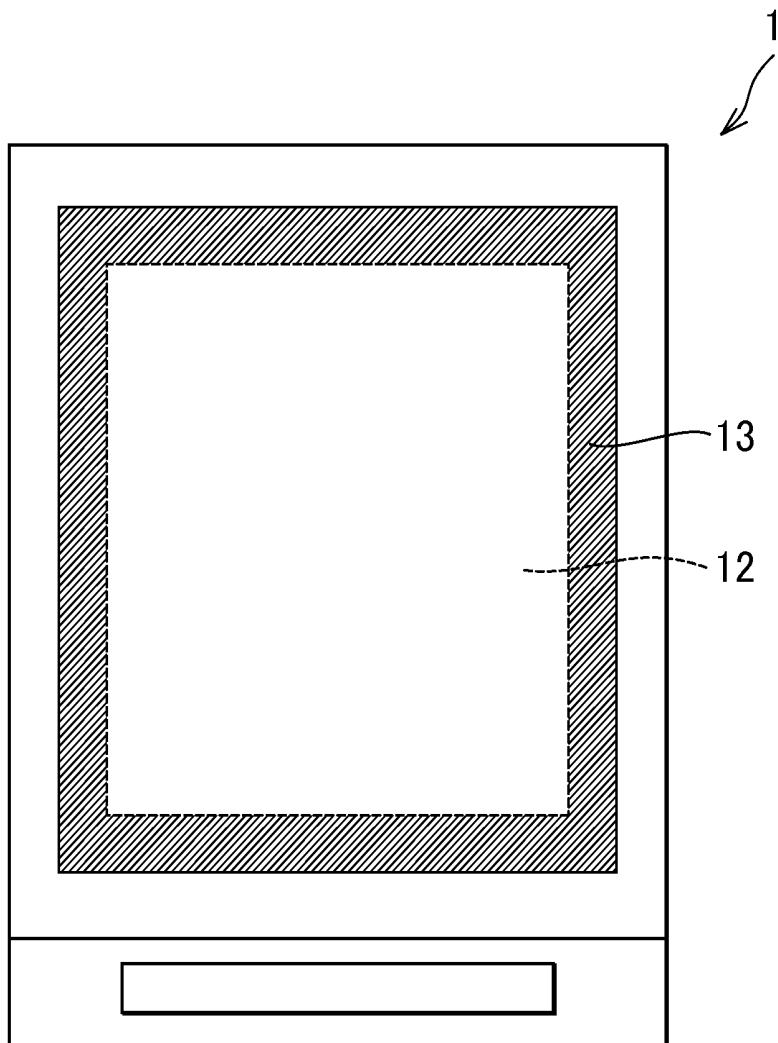


FIG. 5

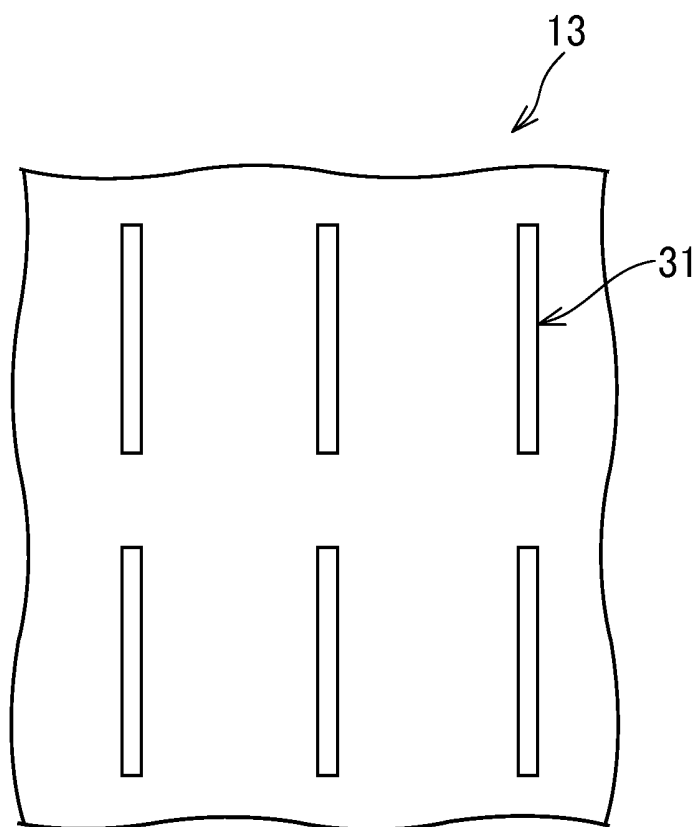


FIG. 6

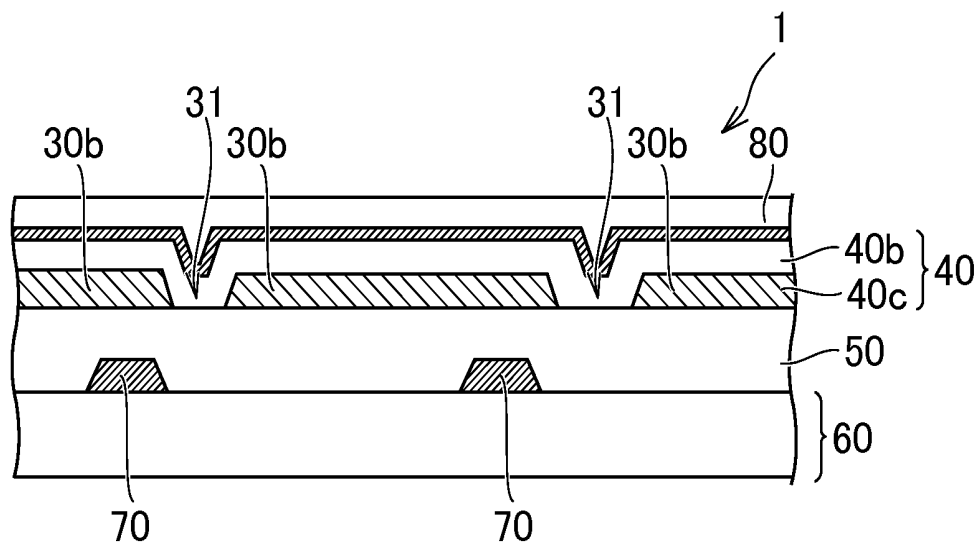


FIG. 7

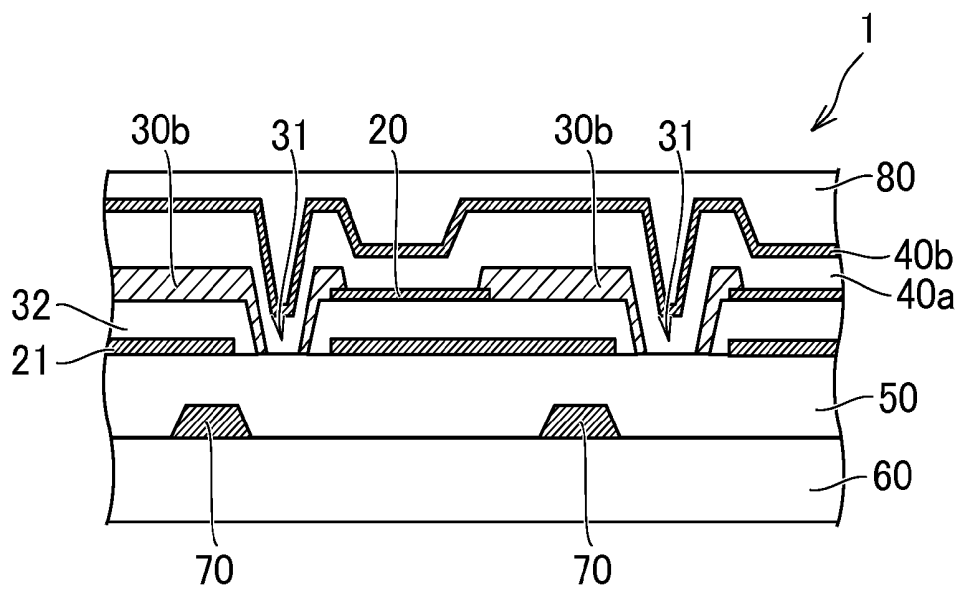


FIG. 8

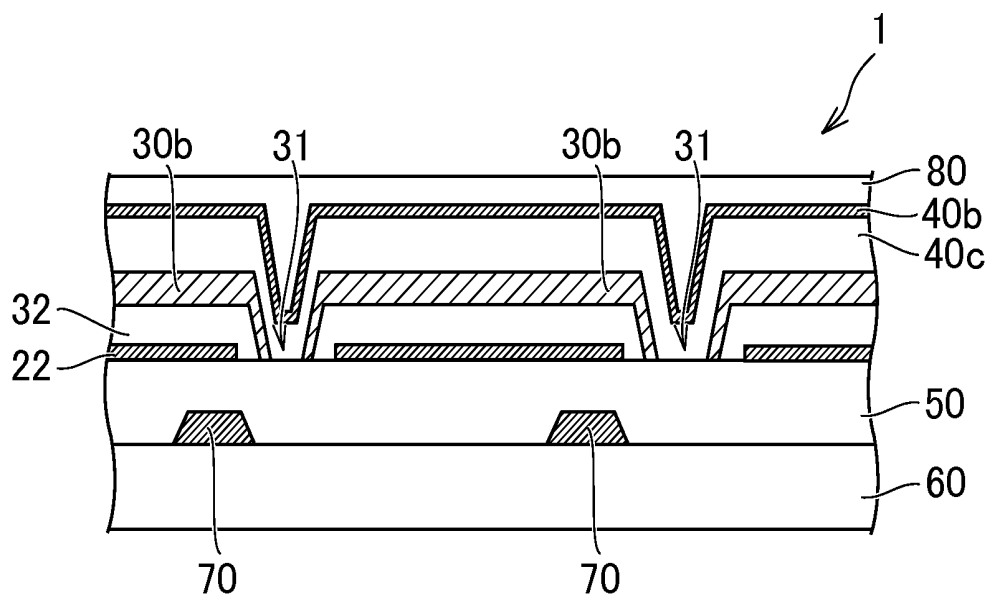


FIG. 9

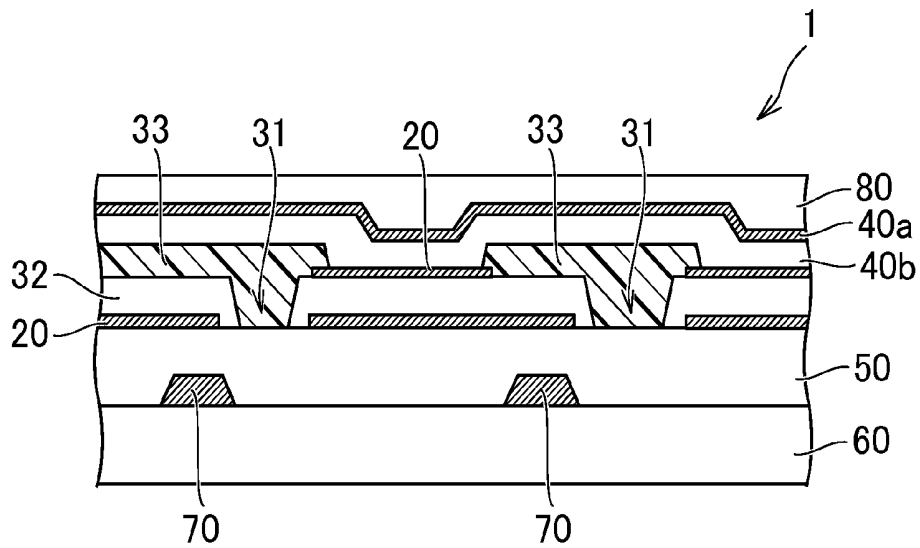


FIG.10

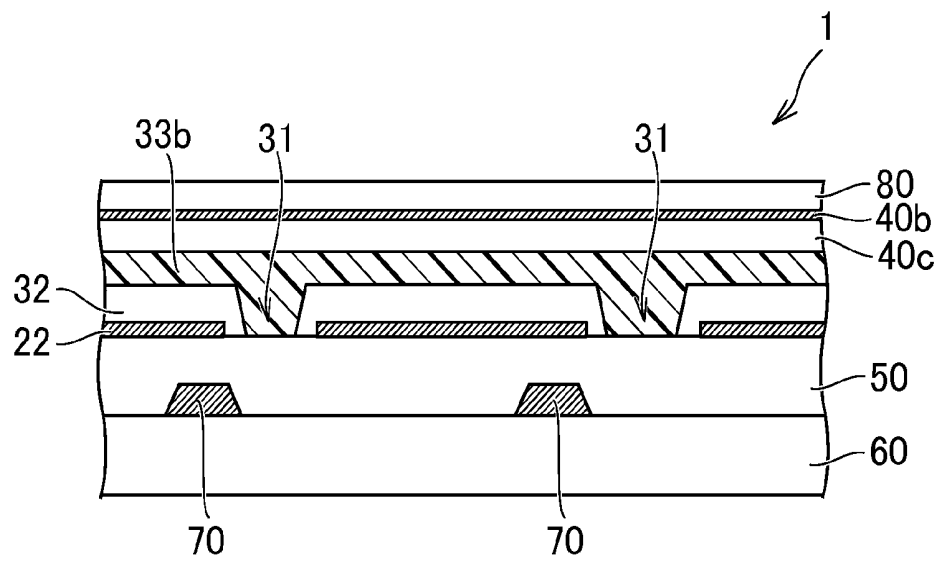
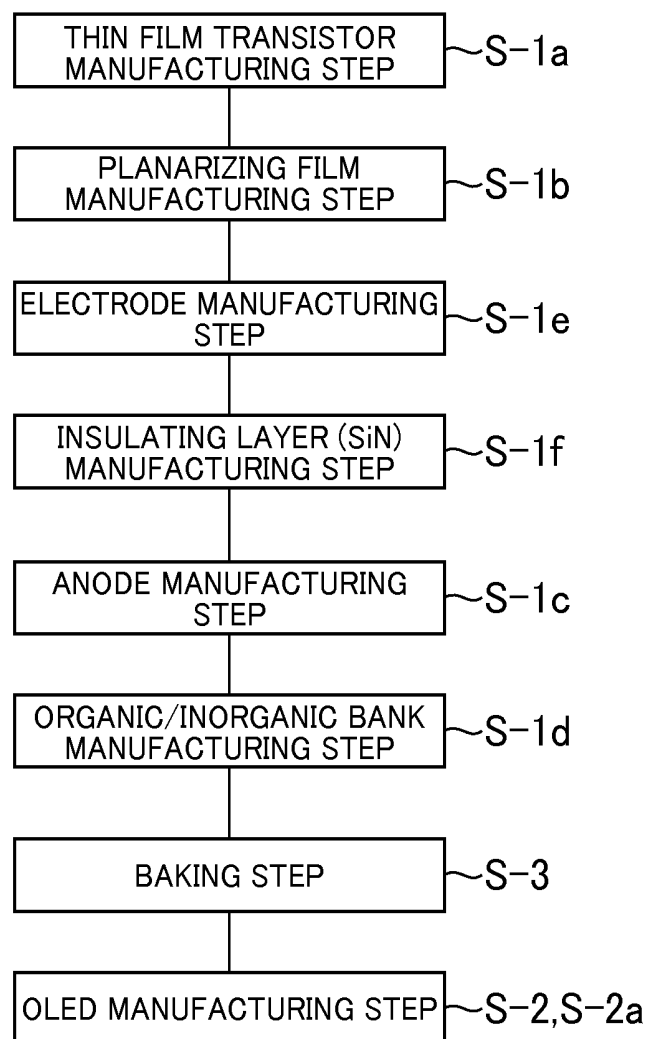


FIG. 11



DISPLAY DEVICE AND MANUFACTURING METHOD THEREOF

CROSS-REFERENCE TO RELATED APPLICATION

The present application claims priority from Japanese patent application JP2013-207211 filed on Oct. 2, 2013, the content of which is hereby incorporated by reference into this application.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a display device and a method of manufacturing the display device.

2. Description of the Related Art

JP 2009-16231 A discloses an organic EL display device including a light emitting area having a lower electrode, an organic layer, and an upper electrode formed in the stated order, a peripheral area disposed in the periphery of the light emitting area, a protective film that covers the upper electrode, and a protective electrode that is electrically connected with the upper electrode, and arranged on an end of the peripheral area for allowing electric charge caused by formation of the protective film to flow out of the peripheral area.

Also, JP 2012-22787 A discloses an organic EL display device including light emitting elements having a function layer which are arranged on a substrate between a first electrode and a second electrode, a partition wall that partitions the function layer for each of light emission areas among the light emitting elements, and a drive circuit that drives the light emitting elements, in which at least a part of the drive circuit is arranged among the light emitting elements in a plane, and an area in which the partition wall is not disposed is present in an area where at least apart of the drive circuit overlaps with the light emitting elements in a plane.

SUMMARY OF THE INVENTION

The organic EL display device using organic light emitting diodes is provided with a structure called "bank" which is arranged around the respective pixel circuits and partitions the respective pixels. The bank is configured to cover an end of an electrode (anode) formed above a TFT substrate to have a function of preventing an electric short-circuiting between an anode and a cathode caused by a step disconnection of an organic EL film layer, and also partitioning light emission of the respective pixels.

For example, when a series of inorganic film is formed on a planarizing film made of an organic material, moisture within the planarizing film cannot be discharged, and the planarizing film and the inorganic film are separated by vaporized moisture.

An object of the present invention is to provide a display device and a method of manufacturing the display device which improve the reliability of an organic EL film layer.

Also, the above and other objects and novel features of the present invention will become apparent from the description of the present specification and the attached drawings.

In order to solve the above problem, according to the present invention, there is provided a display device including: a first substrate in which a plurality of pixel circuits each having a thin film transistor are arranged on an insulating substrate in a matrix; an organic planarizing film that is made of an organic insulating material, and arranged on the first substrate; an electrode that comes in contact with apart of a

surface of the organic planarizing film opposite to the first substrate side; an inorganic bank that is made of an inorganic insulating material, covers an end of the electrode, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side; an OLED layer that covers a side of the electrode and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film; and a sealing film that is configured to cover a side of the OLED layer opposite to the organic planarizing film side.

Also, in order to solve the above problem, according to the present invention, there is provided a method of manufacturing a display device, including: forming a first substrate in which a plurality of pixel circuits each having a thin film transistor are arranged on an insulating substrate in a matrix as a first step; forming an organic planarizing film made of an organic insulating material on the first substrate as a second step; forming an electrode which comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side as a third step; forming an inorganic bank that is made of an inorganic insulating material, covers an end of the electrode, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side as a fourth step; and forming an OLED layer that covers a side of the electrode and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film as a fifth step.

According to the present invention, there is provided a display device and a method of manufacturing the display device which improve the reliability of the organic EL film layer.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1A is a plan view illustrating an organic EL display device according to a first embodiment of the present invention;

FIG. 1B is a cross-sectional view taken along a line 1B-1B in FIG. 1A;

FIG. 2 is a diagram illustrating a manufacturing process of the organic EL display device according to the first embodiment of the present invention;

FIG. 3A is a plan view illustrating an example of an organic EL display device according to a second embodiment of the present invention;

FIG. 3B is a cross-sectional view taken along a line 3B-3B in FIG. 3A;

FIG. 4 is a plan view illustrating an organic EL display device according to an embodiment of the present invention;

FIG. 5 is a partial plan view illustrating opening portions formed in an inorganic layer formed in a peripheral area in the organic EL display device according to the third embodiment of the present invention;

FIG. 6 is a cross-sectional view illustrating the peripheral area in the organic EL display device according to the third embodiment of the present invention;

FIG. 7 is a cross-sectional view illustrating a pixel portion in an organic EL display device according to a fourth embodiment of the present invention;

FIG. 8 is a cross-sectional view illustrating a peripheral area in the organic EL display device according to the fourth embodiment of the present invention;

FIG. 9 is a cross-sectional view illustrating a pixel portion in an organic EL display device according to a fifth embodiment of the present invention;

FIG. 10 is a cross-sectional view illustrating a peripheral area in the organic EL display device according to the fifth embodiment of the present invention; and

FIG. 11 is a diagram illustrating a manufacturing process of the organic EL display device according to the fourth embodiment and the fifth embodiment.

DETAILED DESCRIPTION OF THE INVENTION

An organic EL display device using organic light emitting diodes is provided with a structure called "bank" which is arranged around the respective pixel circuits and partitions the respective pixels. The bank is configured to cover an end of an electrode (anode) formed above a TFT substrate to have a function of preventing an electric short-circuiting between an anode and a cathode caused by a step disconnection of an organic EL film layer, and also partitioning light emission of the respective pixels.

For example, in an organic EL display device of a top emission type, there is a need to reduce a surface step of a TFT substrate so as to form an organic EL film layer as smooth as possible. For that reason, a planarizing film is formed on the TFT substrate. In this example, in order to reduce the surface step of the TFT substrate over which the organic EL film layer is formed, it is desirable to form the planarizing film normally with a thickness of 2 μm to 3 μm taking an uneven difference of the step into account.

Logically, it is not impossible that the planarizing film is made of an inorganic material with the thickness of 2 μm to 3 μm . However, this manner is not realistic because time and effort are spent from the viewpoint of a process. Therefore, the planarizing film is normally made of an organic material such as acrylic resin or polyimide resin.

The electrode (cathode) configuring the organic EL film layer is formed on a part of an upper surface of the planarizing film, and the bank is formed to cover an end of the electrode, and the other surface of the upper surface of the planarizing film in which the electrode is not formed. In this example, the bank is normally formed to cover the overall other surface of the upper surface of the planarizing film on which the electrode is not formed. Conceivably, this is because when the bank is formed to cover the overall other surface of the upper surface of the planarizing film on which the electrode is not formed, the process is simple, and there is no real harm from the viewpoint of performance even if the bank is formed in the above manner.

Also, it is usual that the bank is made of the same material as that of the planarizing film. That is, because the planarizing film is made of the organic material such as acrylic resin or polyimide resin, the bank is similarly made of the organic material. This is because when the bank is made of the same material as that of the planarizing film, the process is simple, and affinity of the respective interfaces is high so that a reduction in the generation of separation of the respective layers from each other can be expected.

If a height of the bank is low, a distance (gap) between the bank and a counter substrate (color filter, etc.) is made shorter, and a precision of coloring (for example, RGB coloring precision) is improved, as a result of which color mixture can be reduced. In order to obtain the effect of reducing the color mixture, it is effective to form the bank with a thickness of 0.5 μm or smaller, preferably 0.2 μm to 0.3 μm . Because the inorganic material can be normally easily formed even if the film thickness is thin as compared with the organic material, the present inventors have considered that it is effective that the bank is made of the inorganic material for the purpose of obtaining this advantage.

However, the combination of the planarizing film made of the organic material with the bank made of the inorganic material suffers from problems described below.

The problem is that in a configuration where the electrode (anode) is formed on the planarizing film, and the bank is formed to cover an end of the electrode, and the other surface of the upper surface of the planarizing film in which the electrode is not formed, (vacuum) baking is implemented as preprocessing before migrating to a light emitting layer formation step for forming the organic EL film layer. This preprocessing is conducted for the purpose of removing the moisture because a large amount of moisture is contained in the organic material forming the planarizing film, and the moisture reduces the reliability of organic EL elements.

In this example, the electrode made of metal, and the bank made of the inorganic material are arranged on the upper surface of the planarizing film made of the organic material to cover the overall upper surface of the planarizing film. For that reason, when the (vacuum) baking is implemented, an escape of the moisture contained in the organic material forming the planarizing film is lost. For that reason, the moisture remaining without being volatilized to an external at the time of (vacuum) baking expands, and has the potential for causing the separation between the bank and the planarizing film, or between the electrode and the planarizing film.

The present inventors have earnestly studied the provision of a display device having the planarizing film made of the organic insulating material, and the bank made of the inorganic insulating material which improves the precision of coloring, and enables a reduction in the color mixture.

Hereinafter, a description will be given of a display device and a method of manufacturing the display device which improve the reliability of the organic EL film layer while reducing the color mixture.

First Embodiment

According to a first embodiment of the present invention, there is provided an organic EL display device including: a first substrate in which a plurality of pixel circuits each having a thin film transistor are arranged on an insulating substrate in a matrix; an organic planarizing film that is made of an organic insulating material, and arranged on the first substrate for planarizing irregularities of a surface of the first substrate; anodes that come in contact with a part of a surface of the organic planarizing film opposite to the first substrate side; an inorganic bank that is made of an inorganic insulating material, covers an end of the anodes, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side; an OLED layer that covers a side of the anodes and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film; and a sealing film that is configured to cover a side of the OLED layer opposite to the organic planarizing film side.

Hereinafter the display device according to an embodiment of the present invention will be described with reference to the accompanying drawings. FIG. 1A is an enlarged plan view of a part of a pixel portion of an organic EL display device according to a first embodiment of the present invention. FIG. 4 is a plan view illustrating an organic EL display device 1 according to a first embodiment of the present invention. Pixels in FIG. 1A are arranged within a display area 12 of the organic EL display device 1 according to the first embodiment of the present invention illustrated in FIG. 4.

As illustrated in FIG. 1A, the organic EL display device 1 according to the embodiment of the present invention has a

first substrate in which plural pixel circuits **100** each having a thin film transistor are arranged on an insulating substrate in a matrix. In the plan view, anodes **20** (pixel electrodes) are arranged at respective positions corresponding to the plural pixel circuits **100** arranged in a matrix, and pixel openings **110** are formed in partial or overall areas of the respective anodes **20**.

Lines **70** that partition the plural pixel circuits **100** in a matrix according to the present invention may be configured by, for example, gate electrode lines Vg (scanning lines), signal lines Vsig, and power supply lines VDD that supply a power to thin film transistors, which are connected to gate electrodes, source electrodes, and drain electrodes included in thin film transistors, respectively.

Also, in the organic EL display device **1** according to the first embodiment of the present invention, an OLED layer (not shown in FIG. 1A) **40** is disposed on upper surfaces of the anodes **20**. The OLED layer (OLED: organic light emitting diode) **40** according to the present invention includes a cathode (transparent electrode: not shown in FIG. 1A), and a light emitting layer **40a**. The light emitting layer **40a** included in the OLED layer **40** is held between the cathode and the anodes **20** arranged at the respective positions corresponding to the plural pixel circuits **100** arranged in a matrix in the plan view.

The anodes **20** are supplied with a current through the thin film transistors disposed on the first substrate. The current that has been supplied to the anodes **20** flows into the cathode through the OLED layer **40** (light emitting layer). In the light emitting layer held between the anodes **20** and the cathode, electrons from the cathode and the holes from the anodes **20** are recombined with each other to emit light. The emitted light is applied to the external through the above pixel openings **110**.

FIG. 1B is a cross-sectional view taken along a line 1B-1B in FIG. 1A. A description will be given of a configuration of the organic EL display device **1** specifically according to the first embodiment of the present invention with reference to FIG. 1B.

The first substrate included in the organic EL display device **1** according to the first embodiment of the present invention is configured in such a manner that the plural pixel circuits **100** each having the thin film transistor are arranged in a matrix on the insulating substrate. In this example, the insulating substrate may be made of, for example, glass or plastic (polycarbonate, polyethylene terephthalate, polyimide, polyacrylate).

Also, the first substrate included in the organic EL display device **1** may be made of, for example, a light transmissive material. In this example, the light transmissive material may be made of glass, plastic (polycarbonate, polyethylene terephthalate, polyimide, polyacrylate), ITO, or IZO, but is not limited to those materials.

Also, a first substrate **60** on which the thin film transistors are arranged is also called "TFT (thin film transistor) substrate". In this example, each of the thin film transistors may include a semiconductor film made of polysilicon, a gate insulating film that covers a semiconductor film, the gate electrode arranged above the semiconductor film through the gate insulating film, and the source electrode and the drain electrode which penetrate the gate insulating film to be electrically connected to the semiconductor film. Also, a drive circuit (not shown) for driving the thin film transistors arranged on the first substrate **60** may be arranged on the first substrate **60**.

Also, the lines **70** that partition the above-mentioned pixel circuits **100** are disposed on the first substrate **60**. The lines **70**

may be configured by, for example, the gate electrode lines Vg (scanning lines), the signal lines Vsig, and the power supply lines VDD that supply a power to thin film transistors, which are connected to the gate electrodes, the source electrodes, and the drain electrodes included in thin film transistors, respectively.

The lines **70** may be made of metal such as aluminum (Al), chromium (Cr), or molybdenum (Mo).

A planarizing film **50** included in the organic EL display device **1** according to the present invention is made of an organic insulating material, and arranged on the first substrate **60**. Also, an upper surface of the planarizing film **50** is planarized, and the upper surface of the planarizing film **50** is flatter than irregularity of a surface of a layer formed on a lower side (first substrate **60** side) of the planarizing film **50**. For example, in the organic EL display device of the top emission type, there is a need to reduce surface steps of the TFT substrate so that the OLED layer **40** becomes as smooth as possible. For that reason, the organic planarizing film **50** is formed on the TFT substrate.

That is, because the lines **70** that partition the pixel circuits **100** are disposed on the first substrate **60**, irregularities caused by a thickness of the lines **70** are present on the surface of the first substrate **60**. The presence of the irregularities makes it difficult to form the anodes **20** and the OLED layer **40** over the first substrate **60** due to step disconnections. For that reason, in order to reduce the irregularities on the first substrate **60**, the organic planarizing film **50** is disposed on the first substrate **60**.

In this example, in order to reduce the surface steps of the TFT substrate on which the OLED layer **40** is formed, the organic planarizing film **50** may be formed with a thickness of 1.5 μm or larger and 3.5 μm or smaller, taking the irregularity difference of the steps into consideration. Also, it is preferable that the organic planarizing film **50** is formed with the thickness of 2 μm or larger, and further it is preferable that the planarizing film **50** is formed with the thickness of 3 μm or smaller.

Also, logically, it is not impossible that the organic planarizing film **50** is made of an inorganic material with the thickness of 1.5 μm or larger and 3.5 μm or smaller. However, this manner is not realistic because time and effort are spent from the viewpoint of a process. Therefore, the organic planarizing film **50** included in the organic EL display device **1** according to the present invention is made of an organic insulating material. More specifically, the organic planarizing film **50** included in the organic EL display device **1** according to the present invention may be made of an organic insulating material selected from a compound group consisting of acrylic resin, polyimide resin, novolac resin, and a mixture of those components.

Also, the organic planarizing film **50** included in the organic EL display device **1** may be formed by, for example, coating the irregularity surface with varnish of an organic resin (liquid product in which organic resin is dissolved in a solvent), and evaporating the solvent contained in the varnish. When the organic planarizing film **50** is thus formed, the varnish flows into recesses of the first substrate **60** surface preferentially, to thereby effectively planarize the irregularities of the surface of the first substrate **60**.

When the organic planarizing film **50** is made of polyimide resin, processing of imidization may be thereafter conducted. Also, when the organic planarizing film **50** is made of an organic thermosetting resin, a heat treatment may be thereafter conducted to facilitate thermosetting. Also, when the organic planarizing film **50** is made of an organic photocurable resin, alight irradiation treatment may be thereafter con-

ducted to facilitate light curing. A material and a formation method of the organic planarizing film **50** are not limited to the above configuration.

The anodes **20** (pixel electrodes) are arranged on the organic planarizing film **50** for planarizing the irregularities of the first substrate **60** surface. That is, the anodes **20** come in contact with a part of a surface of the organic planarizing film **50** opposite to the first substrate **60** side.

Because the anodes **20** function to inject holes into the organic layers such as a hole injection layer or a hole transport layer included in the OLED layer **40**, there is a need to increase a work function. For example, the anodes **20** may be made of tin oxide (SnO_2), zinc oxide doped with aluminum (ZnO:Al), indium tin oxide (ITO), or indium zinc oxide ($\text{In}_2\text{O}_3\text{—ZnO(IZO)}$). Because the work function of ITO is about 4.6 to 5.0 eV, and close to an HOMO level (5.0 to 5.5 eV) of the hole transport material, ITO is suitable for the injection of holes.

Each of the inorganic banks **30** included in the organic EL display device **1** is provided to cover an end of the anode **20**, and come in contact with a part of a surface of the organic planarizing film **50** opposite to the first substrate **60** side. Usually, each of the inorganic banks **30** is formed to cover the ends of the anodes **20**, and the other overall surface of the upper surface of the organic planarizing film **50** in which the anodes **20** are not formed. The reason that the inorganic bank **30** is formed to cover the other overall surface of the upper surface of the organic planarizing film **50** in which the anodes **20** are not formed is because it is conceivable that the process is simple, and there is no real harm from the viewpoint of performance.

However, in this embodiment, the bank **30** does not cover the other overall surface of the upper surface of the organic planarizing film **50** in which the anodes **20** are not formed, and openings **31** are formed in parts of the inorganic layer. For that reason, the bank **30** is formed to expose a part of the upper surface of the organic planarizing film **50** so as to come in contact with the OLED layer **40** without covering the other overall surface of the upper surface of the organic planarizing film **50** in which the anodes **20** are not formed.

Also, the bank **30** is made of the same material as the organic planarizing film **50**. That is, when the organic planarizing film **50** is normally made of an organic material such as acrylic resin or polyimide resin, the bank **30** is also made of the organic material, likewise. However, in the present invention, the bank **30** is made of a material different from that of the organic planarizing film **50**, and made of an inorganic insulating material.

This is because a height of the bank **30** made of the inorganic insulating material can be formed to be lower than the height of the bank made of the organic insulating material. When the bank **30** of the low height is formed, a distance (gap) between the bank **30** and a counter substrate (color filter, etc.) is made shorter, and a precision of coloring is improved, as a result of which color mixture can be reduced.

Also, in order to obtain the effect of reducing the color mixture, it is effective to form the bank **30** with a thickness of 0.15 μm or larger, and 0.35 μm or smaller. Therefore, the height of the bank **30** included in the organic EL display device **1** according to the present invention may be set to be equal to or larger than 0.15 μm , and equal to or smaller than 0.35 μm . Also, the height of the bank **30** may be set to be equal to or smaller than 0.5 μm , or may be set to be equal to or larger than 0.2 μm , and equal to or smaller than 0.3 μm .

Also, the inorganic insulating material of the bank **30** may be selected from a group consisting of silicon nitride, silicon

oxide, and a mixture thereof. Also, the bank **30** may be made of silicon nitride or silicon oxide.

Also, the bank **30** performs a function of covering the end of the anodes **20** separated for each of the pixels to define the light emission areas. That is, each outer edge of the pixel openings **110** is determined by the bank **30** that covers the end of the anode **20**. Also, the banks **30** may be located at positions corresponding to a black matrix (not shown) provided on a color filter substrate (not shown) that faces the first substrate **60** through the OLED layer **40**.

Also, the bank **30** is configured to cover the step of the end of the anodes **20** formed above the first substrate **60** to perform a function of preventing short-circuiting between the anode **20** and the cathode **40b** caused by a step disconnection of the light emitting layer **40a** included in the OLED layer **40**. For that reason, the bank **30** may be formed with a smooth curved surface.

The OLED layer **40** included in the organic EL display device **1** includes the cathode **40b** (transparent electrode) and the light emitting layer **40a** as described above. The light emitting layer **40a** included in the OLED layer **40** is held between the cathode **40b** and the anodes **20** arranged at the respective positions corresponding to the plural pixel circuits **100** arranged in a matrix in the plan view. The anodes **20** are supplied with a current through the thin film transistors disposed on the first substrate **60**. The current that has been supplied to the anodes **20** flows into the cathode **40b** through the light emitting layer **40a**. In the light emitting layer **40a** held between the anodes **20** and the cathode **40b**, electrons from the cathode **40b** and the holes from the anodes **20** are recombined with each other to emit light. The emitted light is applied to the external through the above pixel openings **110**.

The cathode **40b** is a solid electrode formed on an uppermost surface (a surface of the OLED layer **40** opposite to the first substrate **60** side) of the OLED layer **40**. The cathode **40b** is formed over the substantially overall surface of a display surface of the organic EL display device **1**.

In order to inject electrons into the organic layer, it is advantageous that the work function of the cathode **40b** is smaller. For that reason, it is generally preferable that the cathode **40b** is made of metal such as Al, Mg, MgAg, or MgIn. In the organic EL display device **1** of the top emission type such as the organic EL display device **1** according to this embodiment, since the light emitted from the OLED layer **40** is extracted from the cathode **40b** side, the cathode **40b** may be formed of a transparent electrode made of a transparent metal such as indium tin oxide (ITO) or indium zinc oxide ($\text{In}_2\text{O}_3\text{—ZnO(IZO)}$).

The organic EL display device **1** includes a sealing film **80** provided to cover a side of the OLED layer **40** opposite to the organic planarizing film **50** side. The sealing film **80** is provided for protecting the OLED layer **40** from moisture or oxygen from the external. Therefore, a material of the sealing film **80** is selected taking water permeability and air permeability into account.

For example, the sealing film **80** may be made of an inorganic material. Also, the sealing film **80** may be made of a compound selected from a group consisting of SiN, SiO_2 , $\text{P}_2\text{O}_5\text{·SiO}_2$ (PSG), Al_2O_3 , PbO·SiO_2 , Si_3N_4 , SiON, $\text{PbO·B}_2\text{O}_3$, and a mixture of those materials. Also, the sealing film **80** is made of the organic material, and may be made of, for example, polyimide resin and/or derivative thereof. In particular, it is preferable that the sealing film **80** is made of SiN. Also, the sealing film **80** may be deposited by, for example, CVD. The material and the forming method of the sealing film **80** are not limited to the above example.

Also, a thickness of the sealing film **80** may be set to 0.5 μm to 10 μm . If the thickness of the sealing film **80** is set to 0.5 μm to 10 μm , the effect of protecting the OLED layer **40** is enhanced, which is preferable.

If the sealing film **80** is smaller than 0.5 μm , a hole is likely to open in the film. Also, if the sealing film **80** is smaller than 0.5 μm , a waterproof function is impaired. If the sealing film **80** is equal to or larger than 3.0 μm , dust is likely to be coated, which is preferable. Also, if the sealing film **80** is larger than 10 μm , a distance between the color filter arranged to face the TFT substrate and the light emitting surface becomes longer, and color mixture is generated. If the sealing film **80** is larger than 10 μm , there arise such problems that a manufacturing time becomes longer, a film stress becomes larger, and the uniformity of the film is deteriorated.

As illustrated in FIGS. 1A and 1B, the opening **31** where the inorganic bank **30** is not formed between the respective pixels is formed in the inorganic layer. With this configuration, the organic EL display device **1** according to this embodiment has a structure in which apart of the OLED layer **40** comes in direct contact with the organic planarizing film **50**.

The OLED layer **40** in the organic EL display device **1** according to this embodiment comes in direct contact with the organic planarizing film **50** at places other than an area in which the organic planarizing film **50** overlaps with the anodes **20** in a plan view whereby moisture contained in the organic insulating material forming the organic planarizing film **50** is removed by implementing (vacuum) baking. As a result, the moisture is evaporated to the external from the area in which the OLED layer **40** and the organic planarizing film **50** come in direct contact with each other, and the generation of separation between the bank **30** and the organic planarizing film **50**, or between the electrode and the organic planarizing film **50** can be suppressed.

Also, although will be described in the description of a second embodiment in detail later, the first substrate has lines that partition the plural pixel circuits in a matrix, and the OLED layer **40** and the organic planarizing film **50** may come into contact with each other in areas that overlap with the lines. The OLED layer **40** and the organic planarizing film **50** come into contact with each other in the areas that overlap the lines which partition the plural pixel circuits in a matrix in the plan view, to thereby enable the space of the pixel circuits to be saved, or the pixel openings **110** to increase.

Now, a manufacturing process for the organic EL display device **1** will be described specifically, and a step of removing moisture contained in the organic insulating material forming the organic planarizing film **50** by implementing baking in a vacuum will be described specifically.

FIG. 2 is a diagram illustrating a manufacturing process of the organic EL display device **1** according to the first embodiment of the present invention. As illustrated in FIG. 2, the manufacturing process of the organic EL display device **1** is roughly classified into a TFT step (S-1), and an OLED step (S-2). Because it is conceivable that the anodes **20** and the bank **30** formed on the organic planarizing film **50** naturally form the OLED layer **40**, the step of forming the anodes **20** and the bank **30** may be included in an OLED step (S-2). However, in the present invention, for convenience of description, the following description will be made assuming that the step of forming the anodes **20** formed on the organic planarizing film **50**, and the bank **30** is included in a TFT step (S-1).

The TFT step includes a first step S-1a of forming the first substrate **60** in which the plural pixel circuits **100** each having the thin film transistor are arranged on the insulating substrate

in a matrix, a second step S-1b of forming the organic planarizing film **50** made of the organic insulating material for planarizing the irregularities of the surface of the first substrate **60** on the first substrate **60**, a third step S-1c of forming the anodes **20** forming the OLED layer **40**, which comes in contact with a part of a surface of the organic planarizing film **50** opposite to the first substrate **60** side, and a fourth step S-1d of forming the bank **30** made of the inorganic insulating material, which forms the inorganic layer, to cover the end of the anodes **20**, and the surface of the organic planarizing film **50** opposite to the first substrate **60** side. Also, the fourth step S-1d includes the step of forming the openings **31** in the inorganic layer, and exposing a part of the surface of the organic planarizing film **40** opposite to the first substrate **60** side.

The first step S-1a (thin film transistor manufacturing step in FIG. 2) of forming the first substrate **60** in which the plural pixel circuits **100** each having the thin film transistor are arranged on the insulating substrate in a matrix may be conducted through a known photolithographic technology (PEP or lithography).

Then, the second step S-1b (organic planarizing film manufacturing step in FIG. 2) of forming the planarizing film **50** that planarizes the irregularities of the surface of the first substrate **60** obtained by the above-mentioned first step S-1a by the organic insulating material is conducted.

The organic planarizing film **50** may be formed by coating the irregularity surface with varnish of an organic resin (liquid product in which organic resin is dissolved in a solvent) to allow the varnish to flow into the recesses preferentially, and then drying the varnish. Also, the varnish of the organic resin may be coated through a method such as a spin coater or a slit coater, but is not limited to the above methods.

Then, the third step S-1c (anode manufacturing step in FIG. 2) of forming the anodes **20** which form the OLED layer **40**, which come into contact with a part of the surface of the organic planarizing film **50** formed through the above-mentioned second step S-1b opposite to the first substrate **60** side is conducted. In order to remove moisture contained in the organic planarizing film **50** formed before the third step S-1c and after the second step S-1b, a braking (or vacuum baking) process may be conducted, for example, under a condition of 200° C.

Because the organic planarizing film **50** is made of the organic insulating material, the organic planarizing film **50** may absorb the moisture in the atmosphere. Therefore, for the purpose of removing the moisture contained in the organic planarizing film **50** before a process described below, baking (or vacuum baking) process may be conducted.

The anodes **20** may be made of tin oxide (SnO_2), zinc oxide doped with aluminum (ZnO:Al), indium tin oxide (ITO), or indium zinc oxide ($\text{In}_2\text{O}_3\text{—ZnO(IZO)}$), and may be formed through a known photolithographic technology (PEP or lithography).

Then, the fourth step S-1d (bank manufacturing step in FIG. 2) of forming the bank **30** which covers the end of the anodes **20** formed through the above-mentioned third step S-1c, and the surface of the organic planarizing film **50** opposite to the first substrate **60** side to configure the OLED layer **40** by the inorganic insulating material is conducted. The bank **30** may be made of the inorganic insulating material selected from a group consisting of SiN , SiO , and a mixture of those materials, and the bank **30** may be formed through, for example, a CVD method.

In the fourth step S-1d, first, the solid bank **30** is formed to cover the end of the anodes **20** and the overall surface of the organic planarizing film **50** opposite to the first substrate **60**

side in which the anodes **20** are not formed. Thereafter, in the fourth step S-1d, a step of forming the openings **31** in the solid bank **30**, and exposing a part of the surface of the organic planarizing film **50** opposite to the first substrate **60** side is conducted.

Although will be described in detail later, the openings **31** formed in the fourth step are to ensure the escape of moisture so that the escape of the moisture contained in the organic material forming the organic planarizing film **50** is prevented from being lost in implementing (vacuum) baking before the OLED step S-2 when the bank **30** is arranged to cover the overall upper surface of the organic planarizing film **50**. When the escape of moisture is thus ensured, the moisture is evaporated to the external without remaining within the organic planarizing film and expanding at the time of (vacuum) baking, to thereby lead to a reduction in a risk of causing the separation between the bank and the planarizing film, or between the electrode and the planarizing film.

After passing through the above first step S-1a to fourth step S-1d, the TFT step S-1 is completed, and the flow proceeds to the OLED step S-2. In this situation, it is conceivable that a contaminant of fine grains or molecular level may adhere to the obtained TFT substrate. Because the contaminant of this type may cause the deterioration of device characteristics, it is preferable to conduct a cleaning step for removing the contaminant of this type.

Therefore, after the fourth step S-1d, a step of cleaning the obtained TFT substrate with the use of pure water is conducted. The cleaning step may be appropriately conducted together with a brush scrub cleaning, ultrasonic cleaning, or high-pressure jet cleaning.

The OLED step S-2 includes a fifth step S-2a (OLED manufacturing step in FIG. 2) of forming the light emitting layer **40a** that contacts and covers a part of the surface of the organic planarizing film **50** opposite to the first substrate **60** side, which is exposed by the formation of the openings **31** in the inorganic layer, and the surface of the bank **30** opposite to the organic planarizing film **50** side.

In this situation, before the fifth step S-2a, (vacuum) baking may be implemented as a preprocessing, on the TFT substrate obtained in the above TFT step. This is because a large amount of moisture is contained in the organic material forming the organic planarizing film **50** by the above cleaning step, the moisture lowers the reliability of the organic EL element, and therefore the moisture is removed. That is, the method of manufacturing the organic EL display device **1** may include a baking step S-3 of evaporating the moisture contained in the organic material forming the organic planarizing film **50** from the openings **31** of the inorganic layer formed in the fourth step S-1d, and removing the moisture, between the fourth step S-1d and the fifth step S-2a.

Also, the baking step S-3 may include a vacuum baking step. This is because the moisture contained in the organic material forming the organic planarizing film **50** is more surely removed by the execution of the vacuum baking step.

The fifth step S-2a forms the OLED layer **40** that covers one side of the anodes **20** and the bank **30** opposite to the other side that contacts the organic planarizing film **50**, and partially contacts the organic planarizing film **50**. That is, the fifth step S-2a is a step of forming the OLED layer **40** that contacts and covers a part of the surface of the organic planarizing film **50** opposite to the first substrate **60** side, which is exposed by the formation of the openings **31** of the inorganic layer, and the surface of the bank **30** opposite to the organic planarizing film **50** side.

The OLED layer **40** (OLED: organic light emitting diode) according to the present invention includes the cathode **40b**

(transparent electrode), and the light emitting layer **40a** as described above, the light emitting layer **40a** contained in the OLED layer **40** is held between the cathode **40b** and the anodes **20** arranged at the respective positions corresponding to the plural pixel circuits **100** which are arranged in a matrix in the plan view.

Also, because the light emitting layer **40a** is made of an organic material, the light emitting layer **40a** may be formed through, for example, a known coating method. Also, the cathode **40b** (transparent electrode) may be formed through a known vapor deposition method such as CVD.

The organic EL display device **1** according to the first embodiment described above is a display device that improves the reliability of the organic EL film layer.

Also, the display device manufactured by the method of manufacturing the organic EL display device **1** described above includes: the first substrate **60** in which the plural pixel circuits **100** each having the thin film transistor are arranged on the insulating substrate in a matrix; the organic planarizing film **50** that is made of an organic insulating material, and arranged on the first substrate **60** for planarizing the irregularities of the surface of the first substrate **60**; the anodes **20** that come in contact with a part of the surface of the organic planarizing film **50** opposite to the first substrate **60** side; the inorganic bank **30** that is made of the inorganic insulating material, covers the end of the anodes **20**, and comes in contact with a part of the surface of the organic planarizing film **50** opposite to the first substrate **60** side; the OLED layer **40** that covers a side of the anodes **20** and the inorganic bank **30** opposite to a side that comes in contact with the organic planarizing film **50**, and partially comes in contact with the organic planarizing film **50**; and the sealing film **80** that is configured to cover a side of the OLED layer **40** opposite to the organic planarizing film **50** side. The OLED layer **40** may come in direct contact with the surface of a part of the organic planarizing film **50** through the inorganic bank openings **31** formed in the inorganic bank **30**.

When the bank is made of the organic material, because a moisture content is increased as compared with a case the bank is made of the inorganic material, the reliability of the OLED layer (organic EL film layer) whose deterioration is promoted by the moisture is lowered. Also, because the bank made of the organic material is thicker than the bank made of the inorganic material, there is a risk that optical color mixing that the light emitted from the OLED layer is output from the adjacent pixel.

Therefore, the organic EL display device **1** according to the first embodiment having the organic planarizing film **50** made of the organic insulating material, and the inorganic bank **30** made of the inorganic insulating material is a display device that reduces the color mixture and improves the reliability of the organic EL film layer.

Second Embodiment

The organic EL display device **1** according to this embodiment includes: a first substrate **60** in which plural pixel circuits **100** each having a thin film transistor are arranged on an insulating substrate in a matrix; a planarizing film **50** that is made of an organic insulating material, and arranged on the first substrate **60** for planarizing irregularities of a surface of a layer formed on the first substrate **60**; anodes **20** that come in contact with a part of a surface of the planarizing film **50** opposite to the first substrate **60** side; a bank **30** that is made of an inorganic insulating material, covers an end of the anodes **20**, and comes in contact with a part of the surface of the planarizing film **50** opposite to the first substrate **60** side;

13

an OLED layer **40** that covers a side of the anodes **20** and the bank **30** opposite to a side that comes in contact with the planarizing film **50**, and partially comes in contact with the planarizing film **50**; and a sealing film **80** that is configured to cover a side of the OLED layer **40** opposite to the planarizing film **50** side, in which the first substrate **60** has lines **70** for partitioning the plural pixel circuits **100** in the matrix, and the OLED layer **40** and the planarizing film **50** come in contact with each other in an area that overlaps with the lines **70** in a plan view.

The lines **70** that partition the plural pixel circuits **100** in the matrix according to the second embodiment may be configured by any lines **70** selected from the gate electrode lines Vg (scanning lines), the signal lines Vsig, and the power supply lines VDD that supply a power to the thin film transistors, which are connected to the gate electrodes, the source electrodes, and the drain electrodes included in thin film transistors, respectively.

FIG. 3A is a plan view illustrating an example of an organic EL display device **1** according to the second embodiment of the present invention. FIG. 3B is a cross-sectional view taken along a line 3B-3B in FIG. 3A.

As illustrated in FIG. 3A, the organic EL display device **1** according to the second embodiment has the first substrate **60** in which the plural pixel circuits **100** each having the thin film transistor are arranged on the insulating substrate in a matrix. In the plan view, the anodes **20** (pixel electrodes) are arranged at respective positions corresponding to the plural pixel circuits **100** arranged in a matrix, and pixel openings **110** are formed in partial or overall areas of the respective anodes **20**.

As illustrated in FIG. 3A, the openings **31** are arranged in an area that overlaps with the gate electrode lines Vg (scanning lines) in the plan view. For that reason, the OLED layer **40** and the organic planarizing film **50** come in direct contact with each other in an area of the first substrate **60** which overlaps with the gate electrode lines Vg (scanning lines) that partition the plural pixel circuits **100** in the matrix in the plan view.

Because the lines **70** that partition the plural pixel circuits **100** in the matrix do not overlap with the pixel openings **110** in the plan view, the organic EL display device **1** is manufactured without interfering with the pixel opening areas, without causing the separation between the bank **30** and the organic planarizing film **50** or between the electrodes and the organic planarizing film **50** during manufacturing.

The method of manufacturing the organic EL display device **1** according to the second embodiment may be identical with the method of manufacturing the organic EL display device **1** according to the first embodiment except that the first step S-1a in the method of manufacturing the organic EL display device **1** according to the above first embodiment includes a step of forming the lines **70** that partition the plural pixel circuits **100** in the matrix, and the openings **31** formed in the fourth step S-1d are formed in the area that overlaps with the lines **70** in the plan view.

The organic EL display device **1** according to the second embodiment described above is a display device that improves the reliability of the organic EL film layer.

Also, the organic EL display device **1** according to the second embodiment having the organic planarizing film **50** made of the organic insulating material, and the inorganic bank **30** made of the inorganic insulating material is a display device that reduces the color mixture and improves the reliability of the organic EL film layer.

Third Embodiment

FIG. 4 is a plan view illustrating an organic EL display device **1** according to a third embodiment of the present

14

invention. In the organic EL display device **1** according to the third embodiment, a plurality of the pixels illustrated in FIG. **1** described above are arranged to form a display area **12**. A peripheral area **13** (an area marked with diagonal lines in FIG. **4**) surrounding the display area **12** is formed outside of the display area **12**. Lines for transmitting data to the respective pixels, and a dummy pixel that does not contribute to image display are arranged in the peripheral area **13**.

FIG. 5 is a partial plan view illustrating openings **31** formed in an inorganic layer formed in the peripheral area **13** in the organic EL display device according to the third embodiment. FIG. 6 is a cross-sectional view illustrating the peripheral area **13** in the organic EL display device according to the third embodiment. A planarizing film **50** made of an organic material is formed to cover lines **70** on a TFT substrate **60**. An inorganic (SiN) layer **30b** of the same layer as that of the bank is arranged on the organic planarizing film **50** to cover the organic planarizing film **50**. Openings **31** are formed in parts of the inorganic layer **30b**, and the organic layer **40c** of the same layer as that of the light emitting layer **40a** comes in contact with the organic planarizing film **50** through the openings **31**. In FIG. 4, the openings **31** in the peripheral area **13** have the same shape as that of the openings **31** in the display area **12**. However, because the peripheral area **13** has no pixel opening unlike the display area **12**, the openings **31** in the peripheral area **13** may be set to be larger than the pixel openings.

In the above configuration, the baking process illustrated in FIG. 2 can be implemented to remove the moisture contained in the organic planarizing film **50**.

Fourth Embodiment

FIG. 7 is a cross-sectional view illustrating a pixel portion in an organic EL display device according to a fourth embodiment. Parts having the same functions as those in the first embodiment are denoted by identical reference numerals.

In a pixel of FIG. 7, an electrode **21** is arranged in a lower layer of the anode **20** which is a pixel electrode through an insulating film **32**. The electrode **21** forms a capacitor in cooperation with the anode **20** and the insulating film **32**. On the other hand, a storage capacitor is also formed in a circuit layer formed in a lower layer of a planarizing film **50**. The capacitor is formed by the electrode **21** and the anode **20** with the results that a capacitor formed in the circuit layer can be reinforced, and the pixel capacity can increase. In particular, when higher definition is advanced, and a given storage capacity cannot be ensured by only the capacitor formed in the circuit layer, the configuration of FIG. 7 can be employed to ensure a desired capacity.

In this embodiment, the inorganic insulating film **32** is formed to cover the capacitor electrode **21** formed on the organic planarizing film **50**. The insulating film **32** is formed as a series of films partially having the openings **31**. Also, the anodes **20** that are pixel electrodes are formed on the insulating film **32**. The inorganic bank **30** is formed to cover the end of the anode **20** and the opening **31**. The opening **31** is positioned with respect to the opening of the insulating film **32** in a part of the inorganic bank **30**. As a result, the OLED layer **40a** and the planarizing film **50** come into contact with each other through the opening **31**. With this configuration, the moisture of the organic planarizing film **50** can be removed.

In this embodiment, the openings **31** are formed in parts of the inorganic insulating film **32** formed on an overall surface of the planarizing film **50**, thereby being capable of removing the moisture contained in the planarizing film **50**.

15

FIG. 8 is a cross-sectional view illustrating a peripheral area 13 in the organic EL display device according to the fourth embodiment. A planarizing film 50 made of an organic material is formed to cover lines 70 on a TFT substrate 60. Lines 22 of the same layer as that of the capacitor electrode 21 are formed on the planarizing film 50, and an insulating film 32 is formed to cover the lines 22. Openings 31 are partially formed in the insulating film 32. Also, an inorganic (SiN) layer 30b of the same layer as that of the bank is arranged on the insulating film 32, and the opening 31 is formed in the inorganic layer 30b while being positioned with respect to the opening of the insulating film 32. An organic layer 40c and the planarizing film 50 come in contact with each other through the openings 31 formed in the inorganic layer 30b and the insulating film 32.

With the above configuration, the moisture contained in the planarizing film 50 can be removed.

Fifth Embodiment

FIG. 9 is a cross-sectional view illustrating a pixel portion in an organic EL display device according to a fifth embodiment. Parts having the same functions as those in the fourth embodiment are denoted by identical reference numerals.

In this embodiment, as in the fourth embodiment, an insulating film 32 is partially formed with openings 31 as a series of films to cover the electrode 21 forming a capacitor. Each anode 20 that is a pixel electrode is formed on the insulating film 32, and an insulating bank 33 is formed to cover the end of the anode 20, and the opening 31.

The insulating bank 33 is made of an organic material. A lower surface of the insulating bank 33 comes in contact with the planarizing film 50 in the openings 31, and an upper surface of the insulating bank 33 comes in contact with the OLED layer 40b. According to this embodiment, since the insulating bank 33 made of the organic material is intervened between the OLED layer and the planarizing film, the moisture of the planarizing film 50 can be removed without bringing the OLED layer into contact with the planarizing film 50. Also, steps caused by the insulating film can be reduced, and the OLED layer can be formed on the surface having a reduced number of steps. Since the steps are small, tearing of the OLED layer can be prevented.

In this embodiment, since the openings 31 are partially opened in the inorganic insulating film 32 formed over the entire surface of the organic planarizing film 50, the moisture contained in the planarizing film 50 can be removed.

FIG. 10 is a cross-sectional view illustrating a peripheral area 13 in an organic EL display device according to the fifth embodiment. A planarizing film 50 made of an organic material is formed to cover lines 70 on a TFT substrate 60. Lines 22 of the same layer as that of a capacitor electrode 21 are formed on the planarizing film 50. An insulating film 32 is formed to cover the lines 22. Openings 31 are partially formed in the insulating film 32.

An organic film 33b of the same layer as that of the insulating bank 33 is formed on the insulating film 32, and the organic planarizing film 50 and the organic film 33b come in contact with each other through the openings 31. Also, an organic layer 40c of the same layer as that of the OLED layer 40a is formed on an upper surface of the organic film 33b.

With the above configuration, the moisture contained in the planarizing film 50 can be removed.

Sixth Embodiment

FIG. 11 is a diagram illustrating a manufacturing process of the organic EL display device 1 according to the fourth

16

embodiment and the fifth embodiment. As in the step illustrated in FIG. 2, the step of manufacturing the display device according to the present invention is roughly classified into the TFT step (S-1) and the OLED step (S-2). Also, as in FIG. 2, the step of forming the anodes 20 formed on the planarizing film 50 and the bank is included in the TFT step (S-1).

Since the first step S-1a of forming the first substrate 60, and the second step S-1b of forming the planarizing film 50 are identical with those in the first embodiment, their description will be omitted. Also, in order to remove moisture contained in the planarizing film 50, a braking (or vacuum baking) process may be conducted, for example, under a condition of 200° C.

After the second step S-1b, an electrode manufacturing step S-1e of forming the capacitor electrode 21 and the lines 22 of the same layer as that of the capacitor electrode 21 is conducted. In the electrode manufacturing step S-1e, the capacitor electrode and the lines 22 are formed on a surface of the planarizing film 50 formed in the above-mentioned second step S-1b opposite to the first substrate 60 side.

Then, an insulating layer manufacturing step S-1f of coating the electrode 21 and the lines 22 formed in the electrode manufacturing step S-1e is conducted. In this step, the openings 31 are also formed.

Then, an anode manufacturing step S-1c of forming the anodes on the insulating film 32 formed in the insulating layer manufacturing step S-1f is conducted. The anodes 20 may be made of, for example, tin oxide (SnO₂), zinc oxide doped with aluminum (ZnO:Al), indium tin oxide (ITO), or indium zinc oxide (In₂O₃—ZnO(IZO)), and may be formed through a known photolithographic technology (PEP or lithography).

Then, an organic or inorganic bank manufacturing step (bank manufacturing step) S-1d of forming the bank 30 to cover the end of the anodes 20 formed by the above anode manufacturing step S-1c is conducted.

When the organic bank is formed, the organic bank is formed to embed the openings 31 formed in the insulating film manufacturing step S-1f. Also, the organic bank includes the pixel opening on the anodes 20.

In the case of the inorganic bank, the opening is formed in the inorganic bank while being positioned with respect to the openings 31 of the insulating film 32. The inorganic bank has the pixel opening above the anode 20.

As the method of forming the opening, the same method as that in the first embodiment can be applied.

Then, a baking step S-3 and an OLED manufacturing step S-2 are conducted. Because the baking step S-3 and the OLED manufacturing step S-2 are identical with those in the first embodiment, their details will be omitted.

The openings 31 are configured to ensure the escape of the moisture contained in the organic material forming the organic planarizing film 50. When the escape of moisture is thus ensured, the moisture is evaporated to the external without remaining within the organic planarizing film and expanding at the time of (vacuum) baking, to thereby lead to a reduction in a risk of causing the separation between the insulating film and the planarizing film, or between the electrode and the planarizing film.

The organic EL display device 1 according to this embodiment as described above is a display device that reduces the color mixture and improves the reliability of the organic EL film layer.

While there have been described what are at present considered to be certain embodiments of the invention, it will be understood that various modifications may be made thereto,

17

and it is intended that the appended claims cover all such modifications as fall within the true spirit and scope of the invention.

What is claimed is:

1. A display device, comprising:

a first substrate in which a plurality of pixel circuits each having a thin film transistor are arranged on an insulating substrate in a matrix;

an organic planarizing film that is made of an organic insulating material, and arranged on the first substrate;

an electrode that comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side;

an inorganic bank that is made of an inorganic insulating material, covers an end of the electrode, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side;

an OLED layer that covers a side of the electrode and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film; and

a sealing film that is configured to cover a side of the OLED layer opposite to the organic planarizing film side;

wherein an inorganic bank opening portion is formed in the inorganic bank, and wherein the OLED layer comes in contact with the organic planarizing film through the inorganic bank opening portion;

wherein the first substrate has lines for partitioning the plurality of pixel circuits in the matrix, and wherein the inorganic bank opening portion is arranged in an area that overlaps with the lines in a plan view.

2. The display device according to claim 1,

wherein the inorganic insulating material of the inorganic bank is a material selected from a group consisting of silicon nitride, silicon oxide, and a mixture thereof.

3. The display device according to claim 1,

wherein a thickness of the organic planarizing film is equal to or larger than 1.5 μm and equal to or smaller than 3.5 μm , and

wherein a thickness of the inorganic bank is equal to or larger than 0.15 μm and equal to or smaller than 0.35 μm .

4. The display device according to claim 1,

wherein the lines are lines selected from a group consisting of gate electrode lines, scanning lines, signal lines, and power supply lines that supply a power to the thin film transistors, which are connected to gate electrodes, source electrodes, and drain electrodes included in thin film transistors, respectively.

5. A method of manufacturing a display device, comprising:

forming a first substrate in which a plurality of pixel circuits each having a thin film transistor are arranged on an insulating substrate in a matrix as a first step;

18

forming an organic planarizing film made of an organic insulating material on the first substrate as a second step; forming an electrode which comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side as a third step;

forming an inorganic bank that is made of an inorganic insulating material, covers an end of the electrode, and comes in contact with a part of a surface of the organic planarizing film opposite to the first substrate side as a fourth step; and

forming an OLED layer that covers a side of the electrode and the inorganic bank opposite to a side that comes in contact with the organic planarizing film, and partially comes in contact with the organic planarizing film as a fifth step;

wherein the first step includes a step of forming lines for partitioning the plurality of pixel circuits in the matrix, and wherein an inorganic bank opening portion formed in the fourth step is arranged in an area that overlaps with the lines in a plan view.

6. The method of manufacturing a display device according to claim 5,

wherein the fourth step includes a step of forming an inorganic bank opening portion in the inorganic bank, and exposing a part of a surface of the organic planarizing film opposite to the first substrate side, and

wherein the fifth step includes a step of forming the OLED layer that comes in contact with and covers the part of the surface of the organic planarizing film opposite to the first substrate side, and the surface of the inorganic bank opposite to the planarizing film side.

7. The method of manufacturing a display device according to claim 5,

wherein the inorganic insulating material of the inorganic bank is a material selected from a group consisting of silicon nitride, silicon oxide, and a mixture thereof.

8. The method of manufacturing a display device according to claim 5,

wherein a thickness of the organic planarizing film is equal to or larger than 1.5 μm and equal to or smaller than 3.5 μm , and

wherein a thickness of the inorganic bank is equal to or larger than 0.15 μm and equal to or smaller than 0.35 μm .

9. The method of manufacturing a display device according to claim 5,

wherein the lines are any lines selected from scanning lines, signal lines, and power supply lines that supply a power to the thin film transistors, which are connected to gate electrodes, source electrodes, and drain electrodes included in thin film transistors, respectively.

* * * * *

专利名称(译)	显示装置及其制造方法		
公开(公告)号	US9331128	公开(公告)日	2016-05-03
申请号	US14/503453	申请日	2014-10-01
[标]申请(专利权)人(译)	株式会社日本显示器		
申请(专利权)人(译)	日本展示INC.		
当前申请(专利权)人(译)	日本展示INC.		
[标]发明人	TOKUDA NAOKI MIYAMOTO MITSUhide		
发明人	TOKUDA, NAOKI MIYAMOTO, MITSUhide		
IPC分类号	H01L27/32 H01L51/50		
CPC分类号	H01L27/3246 H01L51/50 H01L27/3265 H01L51/5237		
审查员(译)	TAYLOR , EARL		
优先权	2013207211 2013-10-02 JP		
其他公开文献	US20150090993A1		
外部链接	Espacenet USPTO		

摘要(译)

一种显示装置，包括：第一基板；有机平坦化膜，由有机绝缘材料制成，并设置在第一基板上；电极，其与有机平坦化膜的与第一基板侧相对的表面的的一部分接触；无机堤由无机绝缘材料制成，覆盖电极的一端，并与有机平坦化膜的与第一基板侧相对的表面的的一部分接触；OLED层，其覆盖电极的一侧和与有机平坦化膜接触的一侧的无机堤，并且部分地与有机平坦化膜接触；密封膜，其被配置为覆盖OLED层的与有机平坦化膜侧相对的一侧。

